PRODUCT OF THE MONTH · NOVEMBER 2026

SC BLF09 SOLDER PASTE

Reduce nitrogen use. Low voiding.

German-made solder pastes – now available through AdoptSMT.

Solder Chemistry BLF09 is a no-clean solder paste specifically developed for reflow processes in air atmosphere. Depending on the application, nitrogen consumption can be reduced or eliminated. This lead-free, halogen-free, no-clean paste is designed for low voiding.



FOR YOUR SOLDERING PROCESS

- ✓ Reduce or eliminate nitrogen use, depending on the application
- ✓ Low voiding in BGA, CSP and QFN applications
- ✓ Print stability during production pauses

ALLOY OPTIONS AT A GLANCE

Alloy	Silver content	Particle size
SAC305	3.0%	Type 3 / 4
SAC105	1.0%	Type 3 / 4
SAC0307	0.3%	Type 3 / 4

Selected options from the BLF09 datasheet.

Nitrogen savings and voiding performance depend on the application. Suitability is assessed in process trials using the relevant assembly and reflow profile.

PRODUCT DATASHEET

Scan the QR code for technical data.

SC BLF09 FOR YOUR PROCESS

Contact us to discuss your application

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